



EPOXY STRUCTURAL ADHESIVE E-114

E-114 is a low cure temperature, non sag high performance filled single component epoxy adhesive which can be cured at 100°C or 120°C to provide good shear strength in combination with good temperature resistance. Especially suitable for assembly applications such as building precision electric motors or other electromechanical devices. Offers much higher hot bond strength and long term durability than modified acrylic adhesives or conventional epoxies. Has good adhesion to plastics as well as metal and ceramics, not recommended for copper alloys.

PROPERTIES

appearance.....	black viscous paste
specific gravity.....	1.3
viscosity.....	thixotropic
lap shear aluminum to aluminum, cured 2 hour at 100°C, tested at RT.....	3,200 psi
tested at 200°C.....	270 psi
maximum continuous use temperature.....	140°C
maximum short time use temperature.....	200°C
bondline thickness.....	0.0005 in.

CURE CONDITIONS

Cure according to one of the following cure schedules:

2hr 100°C, 1 hr 120°C

All times are for time at the specified temperature as measured at the bondline. Time must be allowed for the bondline to reach temperature. This can be minimized by using high speed curing methods such as infrared, hot air tunnel etc.

STORAGE

Refrigerated storage is desirable. Shelf life is at least 12 months at 0°C, 6 months at room temperature (18°C)

HANDLING

All contact with skin or ingestion should be avoided in accordance with normal handling procedures with epoxy resins. No warranty or guarantee is made regarding this material. The user should determine suitability for a given application. For more information see MSDS.

PRICING

2 oz. jar \$40.00 ea., 12 oz cartridge \$63.00 ea.